

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Akihiko ENDO et al.

Group Art Unit: 2823

Appln. No. : 10/570,663

Examiner: Hsien Ming LEE

I.A. Filed : September 8, 2004

Confirmation No.: 1239

For : METHOD FOR PRODUCING BONDED WAFER

**AMENDMENT UNDER 37 C.F.R. § 1.116**

Commissioner for Patents  
U.S. Patent and Trademark Office  
Customer Service Window, Mail Stop Amendment  
Randolph Building  
401 Dulany Street  
Alexandria VA 22314

Sir:

This is in response to the Office Action mailed March 27, 2008, which sets a three-month shortened statutory period for response, to end June 27, 2008.

Applicants respectfully submit that this response is timely filed and no fee is required for its consideration. However, if any extensions of time are necessary to maintain the pendency of this application, this is an express request for any required extension of time to maintain the pendency of the application, and authorization to charge any required fee to Deposit Account No. 19-0089.

Entry of the instant amendment, with reconsideration and allowance of the application are respectfully requested.

**Amendments to the Claims** begin on page 2 of this paper;

**Remarks** begin on page 5.